



Qualcomm Cloud AI 100 Ultra

Cloud AI 100

PCIe

2023

7nm

OVERVIEW

— FP32 TFLOPS	128 GB VRAM LPDDR4X	548 GB/s Memory Bandwidth	150 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	870.0	8	Standard

MEMORY SPECIFICATIONS

Capacity	128 GB
Type	LPDDR4X
Bandwidth	548 GB/s
Interface Width	—

POWER & EFFICIENCY

TDP	150 W
Est. Max Power	173 W
FP32 Efficiency	—
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Qualcomm	Architecture: Cloud AI 100	Process Node: 7nm
Form Factor: PCIe	Launch Year: 2023	

COMPUTE ENGINE

AI Cores: 64

INTERCONNECT

PCIe: Gen4 x16

ENTERPRISE FEATURES

ECC: Yes